PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date	
Seung-Duk Baek	09/09/2005	
Sun-Won Kang	09/09/2005	
Dong-Ho Lee	09/09/2005	
Jong-Joo Lee	09/09/2005	
Sang-Wook Park	09/09/2005	

RECEIVING PARTY DATA

Name:	Samsung Electronics Co., Ltd.	
Street Address:	416 Maetan-dong, Yeongtong-gu, Suwon-si	
City:	Gyeonggi-do	
State/Country:	KOREA, REPUBLIC OF	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	11305282	

CORRESPONDENCE DATA

Fax Number: (503)274-4622

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 503-222-3613

Email: docketing@techlaw.com

Scott A. Schaffer Correspondent Name:

Address Line 1: 210 SW Morrison Street, Suite 400

Portland, OREGON 97204 Address Line 4:

ATTORNEY DOCKET NUMBER: 9898-462

NAME OF SUBMITTER: Scott A. Schaffer

Total Attachments: 2

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REEL: 017238 FRAME: 0135

PATENT

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PATENT REEL: 017238 FRAME: 0136

PATENT APPLICATION Attorney Docket No.: 9898-462

Client Ref. No.: SS-23387-US

ASSIGNMENT

U.S.A. Patent Application
Sole or Joint
For Inventions Made Outside U.S.A.
Executed With Application

In consideration of the sum of Ten Dollars (10.00) and other good and valuable considerations paid to each of the undersigned, to wit:

- (1) Seung-Duk BAEK
- (2) Sun-Won KANG
- (3) Dong-Ho LEE
- (4) Jong-Joo LEE
- (5) Sang-Wook PARK

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the receipt and sufficiency of which are hereby acknowledged by the undersigned who hereby sell(s), assign(s) and transfer(s) unto:

SAMSUNG ELECTRONICS CO., LTD. 416 MAETAN-DONG, YEONGTONG-GU SUWON-SI, GYEONGGI-DO REPUBLIC OF KOREA

(hereinafter designated "ASSIGNEE") the entire right, title and interest in and to the invention as defined in 35 USC §100, for the United States of America, the invention entitled:

SEMICONDUCTOR PACKAGE MODULE WITHOUT A SOLDER BALL AND METHOD OF MANUFACTURING THE SEMICONDUCTOR PACKAGE MODULE

for which an application for Letters Patent of the United States of America has been executed even date herewith by the undersigned, and in and to any and all divisionals, continuations, substitutes, and reissues thereof; and all resulting patents and the undersigned hereby authorizes and requests the United States Assistant Commissioner of Patents to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

And the undersigned hereby agrees to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

PATENT REEL: 017238 FRAME: 0137 Please sign
concurrently
with Oath or Declaration
and Power of Attorney

SIGNED ON THE DATES INDICATED BESIDE OUR SIGNATURES:

INVENTOR(S)	DATE SIGNED	WITNESSED
(1) Seungcluk Back. Seung-Duk BAEK	09 September, 2005	
(2) Sunwon Kang Sun-Won KANO	of sex., not	
(3) Doysler Two Dong-Ho LEE	09 Squembar 2005	
(4) Jong-Joo LEE	09 Sept. 2005	
(5) Sony-Wook Jones Sang-Wook PARK	E of Septender Just	

PLEASE RETURN RECORDED ASSIGNMENT TO:

Alan T. McCollom Marger Johnson & McCollom 210 S.W. Morrison Street, Suite 400 Portland, OR 97204

RECORDED: 03/01/2006